

Automatic Ball Wire Bonder

Model: SA-BWB-6000Plus

SA-BWB-6000Plus is an automatic ball wire bonder. It is equipped with programmable auto-varifocal optics, dual-frequency transducer and rigid platform. Featuring reliable motion control, advanced material handling and multi-channel EFO, it ensures consistent bonding for microwave components, lasers, optical communication, sensors, MEMS and power devices.



Feature

- Dual-Frequency transducer
- High rigidity heater block
- High reliable motion control system
- Programmable automatic material handling system
- Programmable Focus Optics
- Rigid X-Y Table system

Application

- Microwave components
- Lasers
- Optical communication devices
- Sensors
- MEMS
- RF modules
- SAW devices
- Power devices
- Discrete devices

Specifications:

Parameter	Descriptions
Bonding Accuracy	$\pm 2 \mu\text{m}@3\sigma$
Bonding Stroke	X=60mm, Y=70mm (LF width $\leq 80\text{mm}$)
Length of Wire Bonding	$\leq 7\text{mm}$
Min Bond Pad Pitch	$45\mu\text{m}$
Loop Types	Q-loop / SQ-loop / BGA-TWS
Spool Diameter	50mm (2 inches)
Wire Bonding Capacity(max.)	30,000 wires/panel
Bonding Wire Type	Gold wire, copper wire, palladium-coated copper wire, silver wire, alloy wires (18~50 μm)
Bonding Speed	45ms (2mm wire length)
Operating System	Windows
Optical System	Option between $\times 2 \sim \times 4$ and $\times 1.6 \sim \times 3.6$ times, both with programmable focus
Weight	650Kg
Input Voltage	220V $\pm 10\%$ @50~60Hz
Power	1.2KW
Compressed Air Pressure	$\geq 0.35\text{MPa}$
Size(L×W×H)	1000mm×1300mm×1700mm